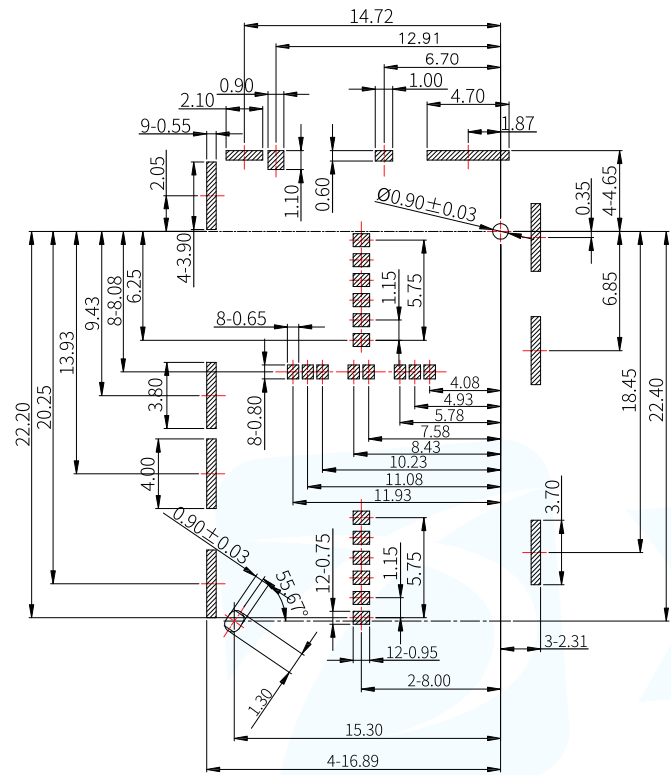


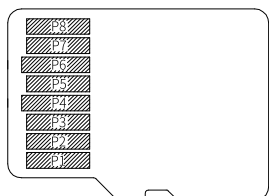
NOTES:  
 1.FINISH  
 (1)CONTACT: CONTACT AREA: Au 15u" Min;SW AREA: Au 5u" Min; GOLD PLATING ON SOLDER AREA,3u" Min.  
 (2)SHELL: SOLDER AREA: Au 3u" Min. SOLDER AREA: Au 3u" Min.  
 2.ELECTRICAL REQUIREMENTS:  
 (1)CURRENT RATING: 0.3A PER PIN.  
 (2)CONTACT RESISTANCE: 60 m0hm MAX. AFTER TEST: 100 m0hm MAX SWITCH RESISTANCE: 100 m0hm MAX. AFTER TEST: 150 m0hm MAX  
 (3)INSULATION RESISTANCE: 1,000 M0hm MIN. 200 VDC FOR 1 MINUTE  
 (4)WITHSTANDING STRENGTH: 500V AC FOR 1 MINUTE  
 3.MECHANICAL REQUIREMENTS:  
 (1)TRAY MATING FORCE: 2~10N;TRAY UNMATING FORCE: 6~10N OPERATING FORCE: 4~15N THE RESORPTION DISTANCE OF THE TRAY: 0.4mm MIN  
 (2)DURABILITY: 3,000 CYCLES MIN.  
 4.ENVIRONMENT REQUIREMENTS:  
 (1)OPERATING TEMP: -30°C TO +85°C  
 (2)STORAGE TEMPERATURE: -40°C TO +85°C

NO.	PART NAME	Q'TY	MATERIAL	FINISH
1	CONTACT	1	Copper alloy	Plating Ni 30~200u over all Contact Area: Au 15u" min Switch Area: Au 5u" min Solder Area: Au 3u" min
2	I/M HOUSING	1	LCP	BLACK COLOR,UL94V-0
3	SHELL	1	SUS301	Plating Ni 10~50u" over all Solder Area: Au 3u" min
4	LEVER	1	SUS301	NO PLATING
5	CAM	1	SUS304	NO PLATING
6	RI/M Latch	1	SUS301+Nylon	NO PLATING,Black Plastic
7	LI/M Latch	1	SUS301+Nylon	NO PLATING,Black Plastic
8	Switch	1	Copper alloy	Plating Ni 30~200" over all Switch Area: Au 15u" min Solder Area: Au 3u" min

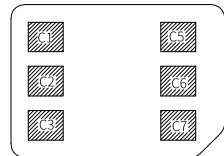
MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 1.35H Nano&tft 3in2 with tray(pin push)Conn.Assem.
			PAR MCS-302-C1
DECIMALS:	ANGLES:		DWN KING 2018.06.05
X:±0.5	X:±2°		CHKD
X.X:±0.20	X.X:±1°	APVD	
X.XX:±0.10		SCALE 1:1	UNIT: mm
CUSTOMER COPY		SIZE:A4	SHEET:1F4
			REV:A



RECOMMENDED PCB LAYOUT(SOLDER AREA)  
(TOLERANCE:±0.05)  
PASTE BOARD THICKNESS 0.10mm.  
SOLDER AREA



Micro SD CARD ELECTRICAL



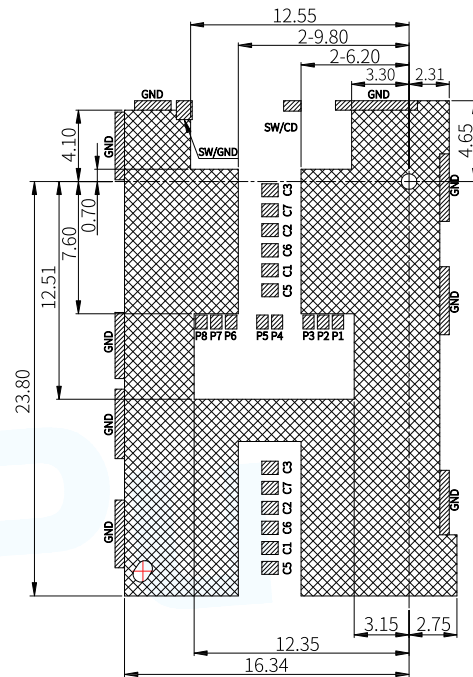
NANO SIM CARD ELECTRICAL

CONNECTOR PIN ASSIGNMENT:

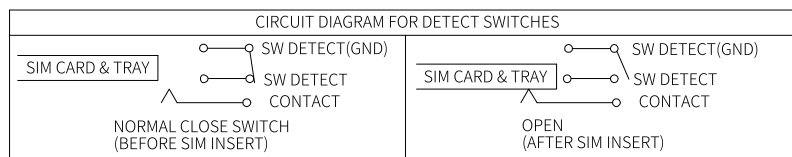
ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
SW	TRAY DETECTION SW
S	SHELL GND
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

CARD PIN ASSIGNMENT:

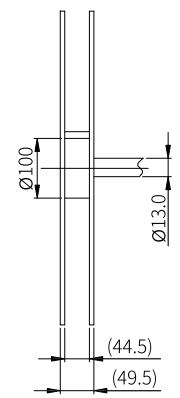
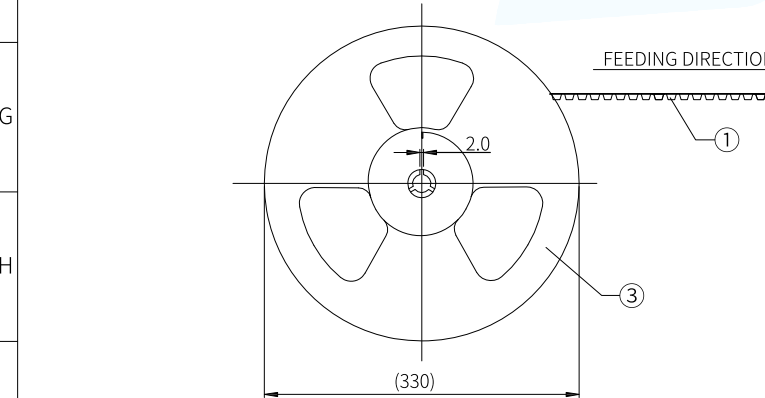
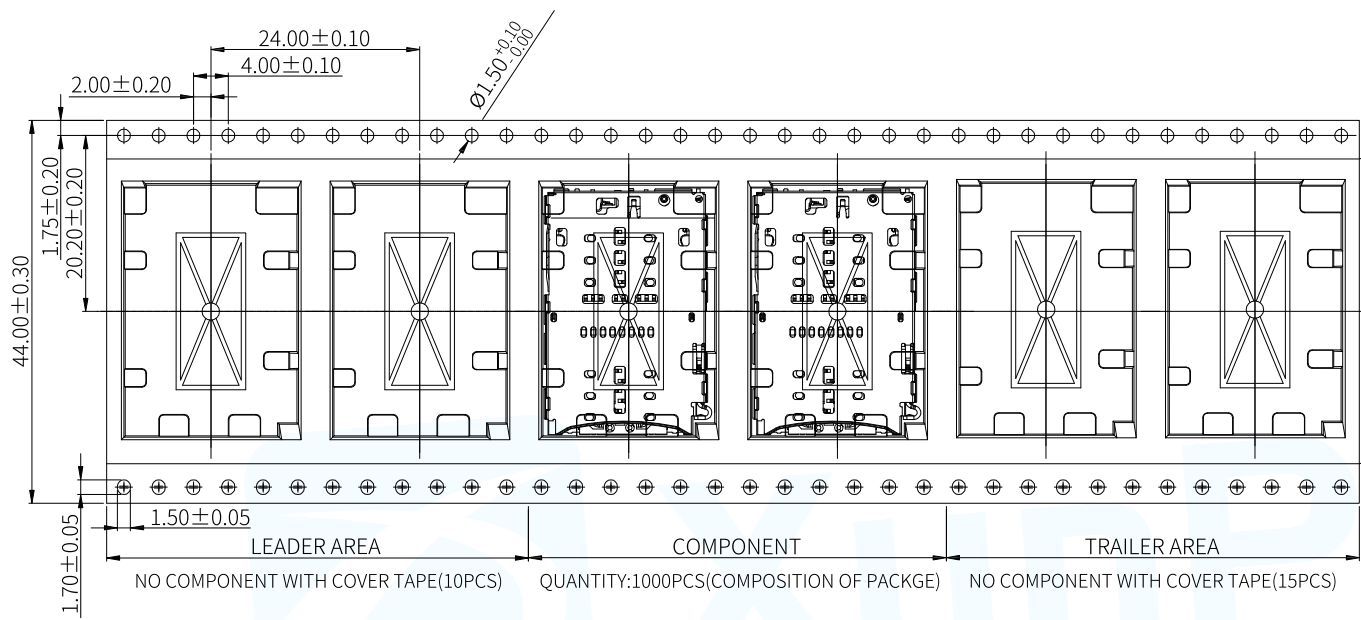
ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DAT3 OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM



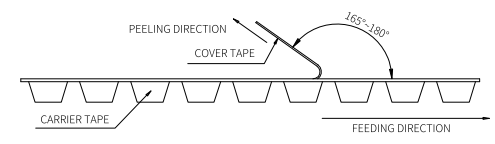
RECOMMENDED PCB LAYOUT(NO PATTERNS)  
(TOLERANCE:±0.05)  
NO PATTERNS



MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 1.35H Nano&tf 3in2 with tray(pin push)Conn.Assem.		
DECIMALS:	ANGLES:		PAR	MCS-302-C1	
X:±0.5	X:±2°		DWN	KING	2018.06.05
X.X:±0.20	X.X:±1°		CHKD		
X.XX:±0.10		APVD			
CUSTOMER COPY		SCALE 1:1	UNIT: mm		
		SIZE:A4	SHEET:2F4	REV:A	



NOTES:  
 1. POCKET HOLE PITCH CUMULATIVE TOLERANCE  $\pm 0.40$ mm  
 2. COVER TAPE PEELING STRENGTH: 0.01~0.13kg AT 300mm/MIN



**A3** 3. PACKAGING CAPACITY  
 1000PCS/REEL; 6REEL/CARTON; TOTAL:6000PCS/CARTON  
 4. PACKAGING USE ATTENTION  
 NOT TWISTED OVER 90° WITHIN 1000mm

MANUFACTURE DWG		 东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd			
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 1.35H Nano&tf 3in2 with tray(pin push)Conn.Assem.		
			PAR	MCS-302-C1	
DECIMALS:			DWN	KING	2018.06.05
X: $\pm 0.5$			CHKD		
X.X: $\pm 0.20$		APVD			
X.XX: $\pm 0.10$		SCALE 1:1	UNIT: mm		
		CUSTOMER COPY	SIZE:A4	SHEET:3F4	REV:A